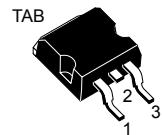
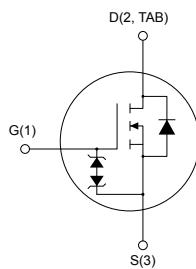


Automotive-grade N-channel 400 V, 0.063 Ω typ., 38 A, MDmesh™ DM2 Power MOSFET in a D²PAK package

Features



D²PAK



AM0147SV1

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STB45N40DM2AG	400 V	0.072 Ω	38 A	250 W

- AEC-Q101 qualified 
- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

This high-voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast-recovery diode series. It offers very low recovery charge (Q_{rr}) and time (t_{rr}) combined with low $R_{DS(on)}$, rendering it suitable for the most demanding high-efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.



Product status	
STB45N40DM2AG	

Product summary	
Order code	STB45N40DM2AG
Marking	45N40DM2
Package	D ² PAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_{case} = 25^\circ\text{C}$	38	A
	Drain current (continuous) at $T_{case} = 100^\circ\text{C}$	24	
$I_{DM}^{(1)}$	Drain current (pulsed)	110	A
P_{TOT}	Total power dissipation at $T_{case} = 25^\circ\text{C}$	250	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	
T_{stg}	Storage temperature range	-55 to 150	$^\circ\text{C}$
T_j	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2. $I_{SD} \leq 38 \text{ A}$, $di/dt = 800 \text{ A}/\mu\text{s}$, V_{DS} peak < $V_{(BR)DSS}$, $V_{DD} = 80\%$ $V_{(BR)DSS}$
3. $V_{DS} \leq 320 \text{ V}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.5	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	30	

1. When mounted on an 1-inch² FR-4, 2 Oz copper board.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	7	A
$E_{AS}^{(2)}$	Single pulse avalanche energy	1100	mJ

1. Pulse width is limited by T_{jmax} .
2. starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50 \text{ V}$

2 Electrical characteristics

($T_{case} = 25^\circ\text{C}$ unless otherwise specified)

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	400			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 400 \text{ V}$			10	μA
		$V_{GS} = 0 \text{ V}, V_{DS} = 400 \text{ V}, T_{case} = 125^\circ\text{C}^{(1)}$			100	
I_{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 5	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3	4	5	V
$R_{PS(on)}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 19 \text{ A}$		0.063	0.072	Ω

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	2600	-	pF
C_{oss}	Output capacitance		-	180	-	
C_{rss}	Reverse transfer capacitance		-	3.5	-	
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 320 \text{ V}, V_{GS} = 0 \text{ V}$	-	300	-	pF
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	4	-	Ω
Q_g	Total gate charge	$V_{DD} = 320 \text{ V}, I_D = 38 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	56	-	nC
Q_{gs}	Gate-source charge		-	13	-	
Q_{gd}	Gate-drain charge		-	28	-	

1. $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 200 \text{ V}, I_D = 19 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	20	-	ns
t_r	Rise time		-	6.7	-	
$t_{d(off)}$	Turn-off delay time		-	68	-	
t_f	Fall time		-	9.8	-	

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		38	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		110	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$, $I_{SD} = 38 \text{ A}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 38 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_{DD} = 60 \text{ V}$	-	95		ns
Q_{rr}	Reverse recovery charge	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	0.4		μC
I_{RRM}	Reverse recovery current		-	8.5		A
t_{rr}	Reverse recovery time		-	185		ns
Q_{rr}	Reverse recovery charge	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	1.62		μC
I_{RRM}	Reverse recovery current		-	17.5		A

1. Pulse width is limited by safe operating area.

2. Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 250 \mu\text{A}$, $I_D = 0 \text{ A}$	± 30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

2.1 Electrical characteristics (curves)

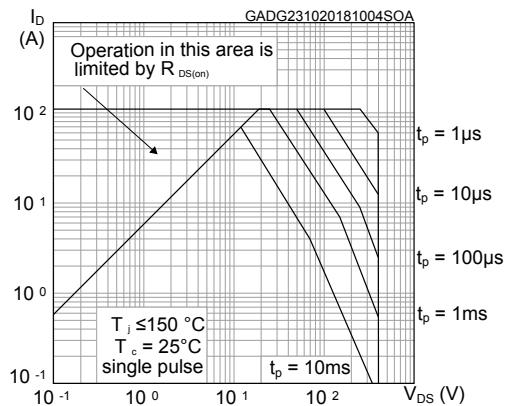
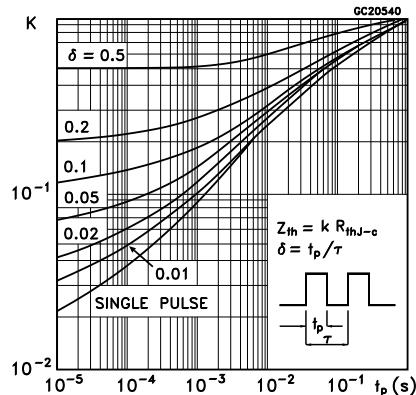
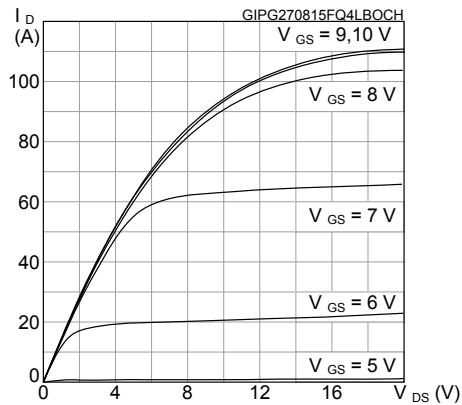
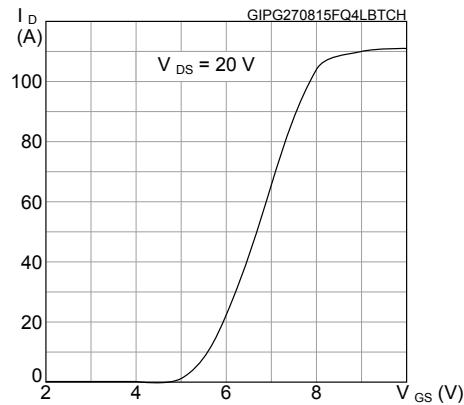
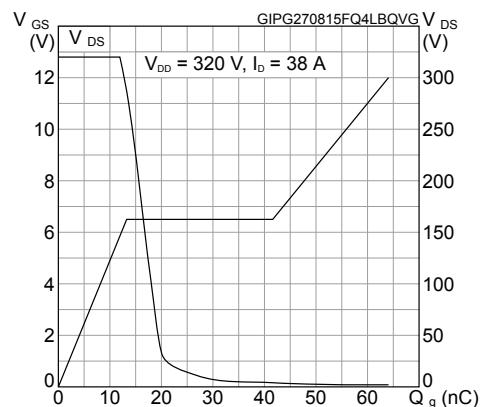
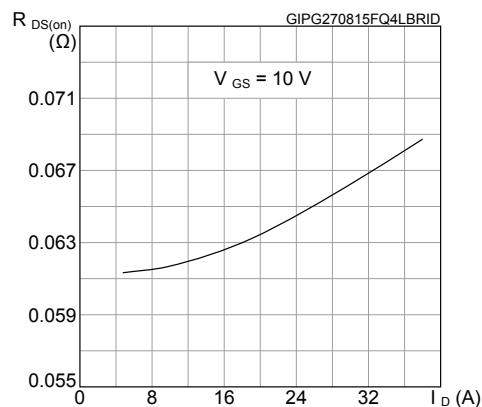
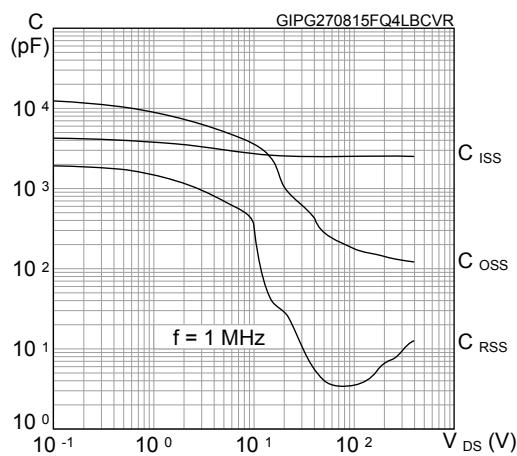
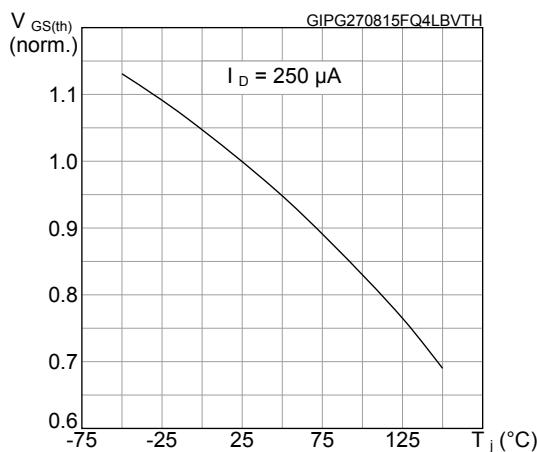
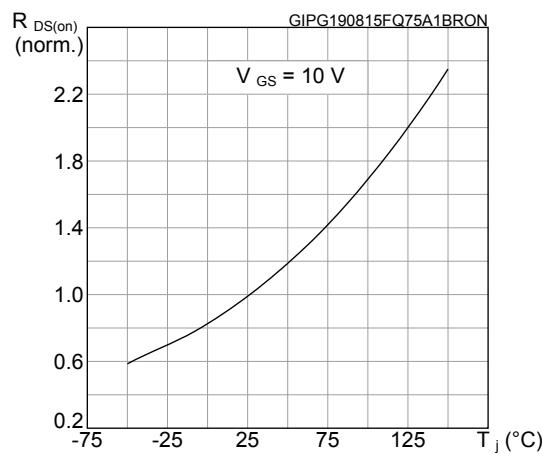
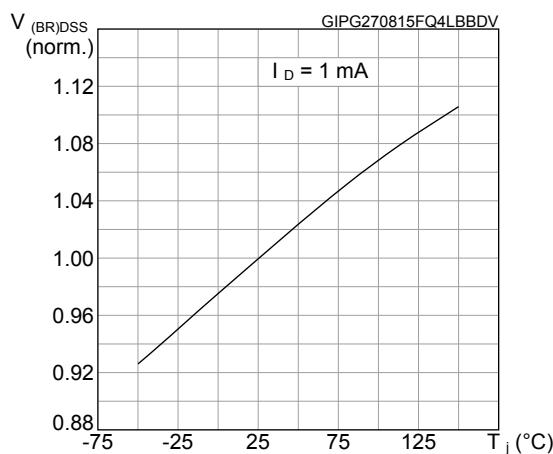
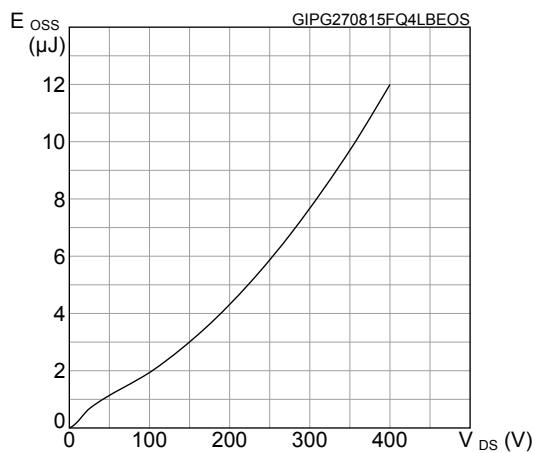
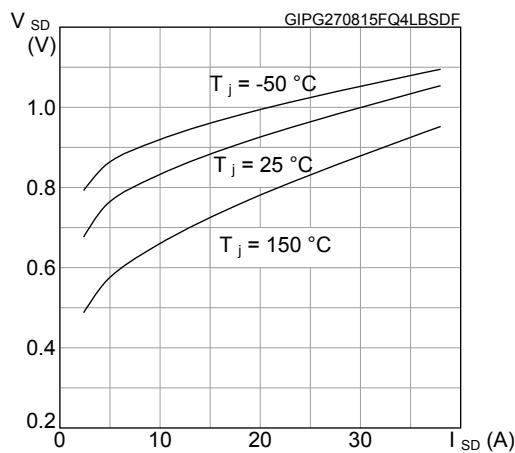
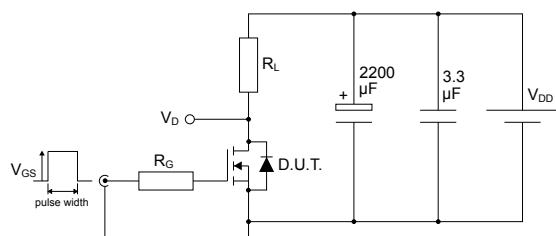
Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Gate charge vs gate-source voltage

Figure 6. Static drain-source on-resistance


Figure 7. Capacitance variations

Figure 8. Normalized gate threshold voltage vs temperature

Figure 9. Normalized on-resistance vs temperature

Figure 10. Normalized V_(BR)DSS vs temperature

Figure 11. Output capacitance stored energy

Figure 12. Source- drain diode forward characteristics


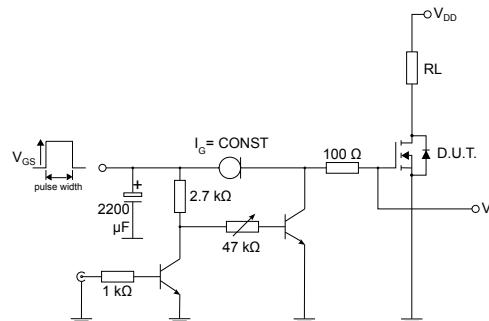
3 Test circuits

Figure 13. Test circuit for resistive load switching times



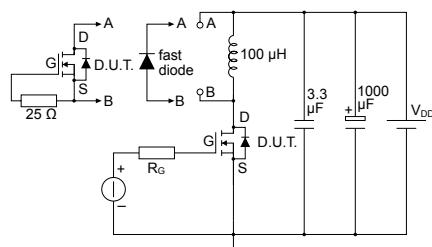
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Figure 14. Test circuit for gate charge behavior



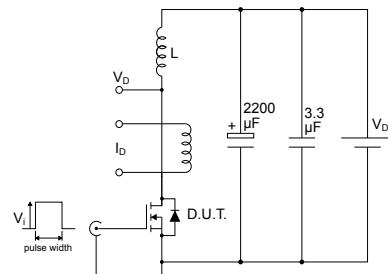
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Figure 15. Test circuit for inductive load switching and diode recovery times



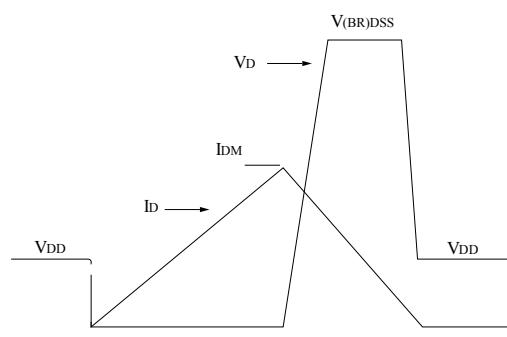
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Figure 16. Unclamped inductive load test circuit



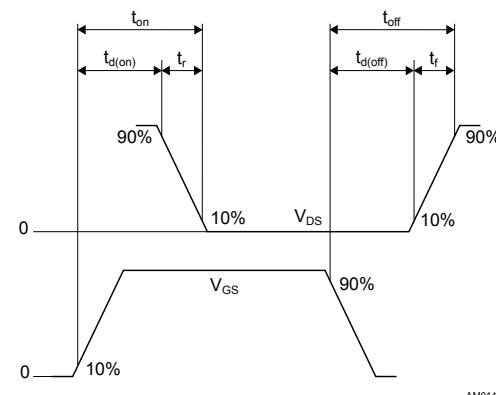
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Figure 17. Unclamped inductive waveform



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Figure 18. Switching time waveform



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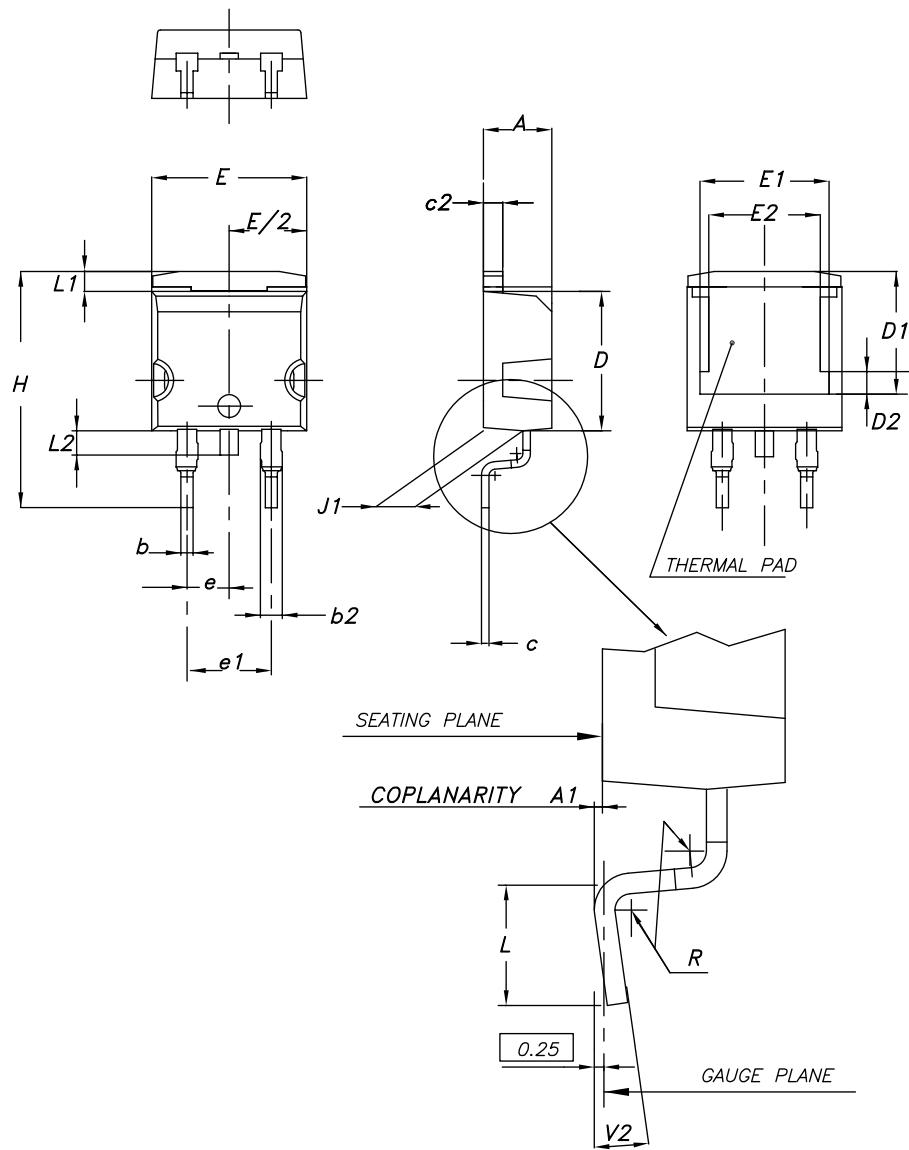
4

Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 D²PAK (TO-263) type A2 package information

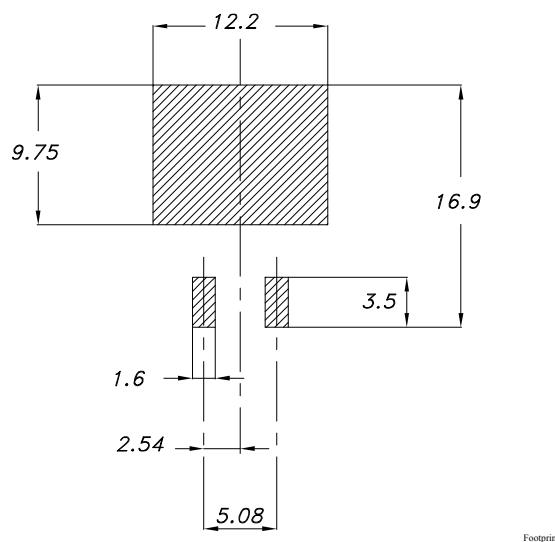
Figure 19. D²PAK (TO-263) type A2 package outline



0079457_A2_25

Table 9. D²PAK (TO-263) type A2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.70	8.90	9.10
E2	7.30	7.50	7.70
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

Figure 20. D²PAK (TO-263) recommended footprint (dimensions are in mm)

4.2 D²PAK packing information

Figure 21. D²PAK tape outline

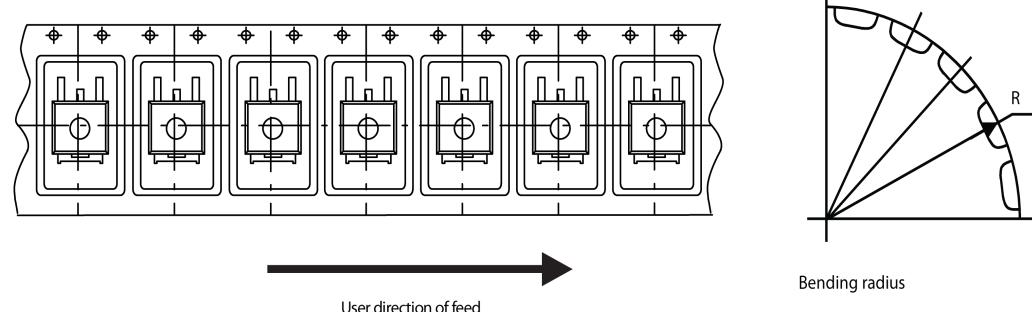
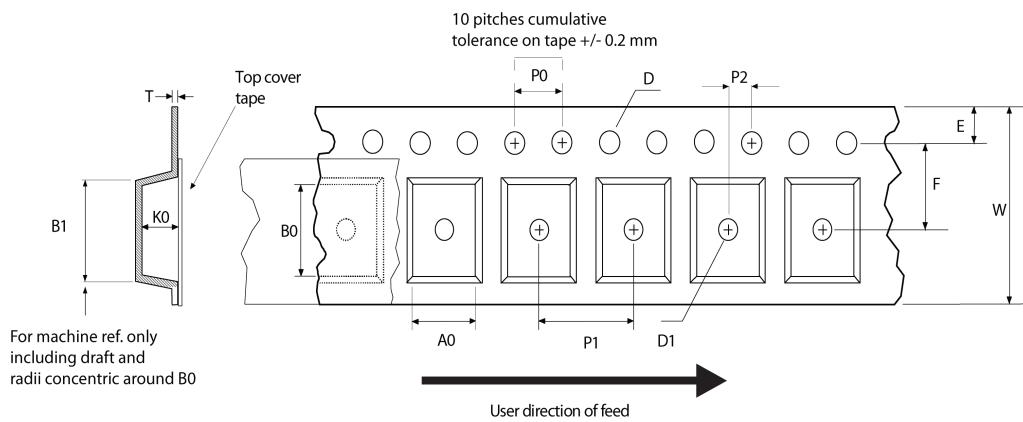
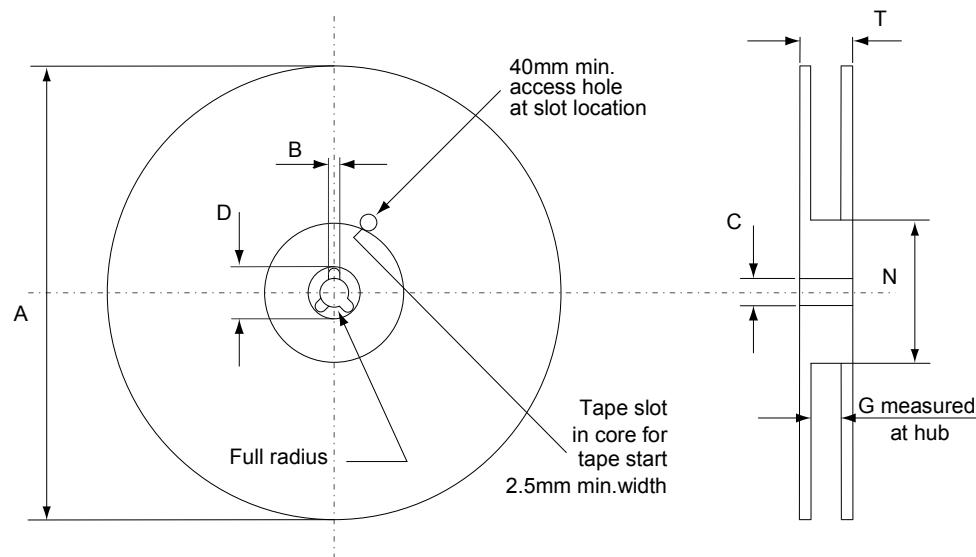


Figure 22. D²PAK reel outline

AM06038v1

Table 10. D²PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Revision history

Table 11. Document revision history

Date	Revision	Changes
27-Aug-2015	1	Initial version
04-Aug-2016	2	Updated <i>Figure 2: "Safe operating area"</i> . Minor text changes.
14-Feb-2018	3	Removed maturity status indication from cover page. Updated <i>Section 4.1 D²PAK (TO-263) type A2 package information</i> . Minor text changes
23-Oct-2018	4	Updated <i>Table 1. Absolute maximum ratings</i> and <i>Table 7. Source-drain diode</i> . Updated <i>Figure 1. Safe operating area</i> and <i>Figure 14. Test circuit for gate charge behavior</i> . Minor text changes.

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